



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Small et al.
Title: Compositions for Chemical Mechanical Planarization of Copper
Application No.: 10/017,934 Filing Date: December 12, 2001
Examiner: Lynette T. Umez Eronini Group Art Unit: 1765
Docket No.: CHEM.001US0 Conf. No.: 1435

Certificate of Mailing Under 37 CFR 1.8

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Gailen Bower
Signature

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

SUBMISSION OF FORMAL DRAWING

Dear Sir:

One (1) formal drawing sheet, consisting of Figure 1, in the above-named application, is hereby submitted. If there are any questions regarding these drawings, please call the undersigned.

Respectfully submitted,

K. Alison de Runtz
K. Alison de Runtz
Reg. No. 37,119

Nov. 30, 2004
Date

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